

SUPPLEMENTARY MATERIAL TO
**Tuning the copper cluster's size on HOPG by electrodeposition
from perchlorate aqueous solutions. An AFM study**

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J. Serb. Chem. Soc. 84 (12) (2019) 1415–1426

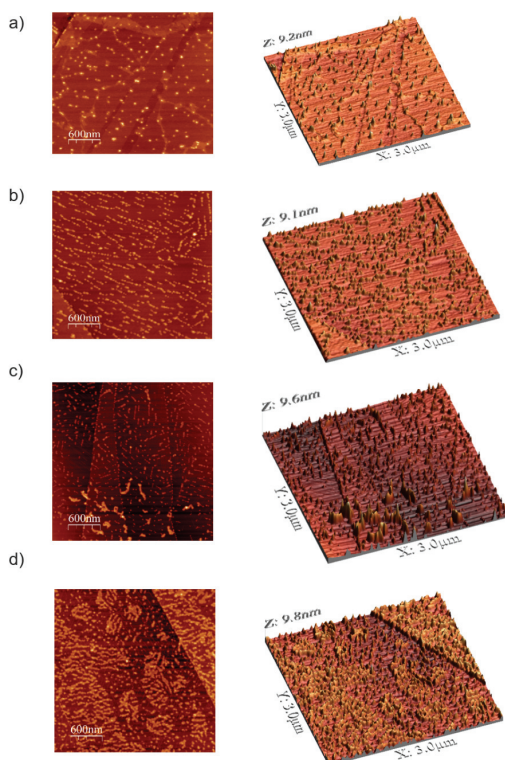


Fig. S-1. AFM images of the copper clusters electrodeposited on HOPG electrode at: a) -0.075 , b) -0.125 , c) -0.150 and d) -0.175 V applied potentials from a plating bath containing 0.01 M $\text{Cu}(\text{ClO}_4)_2$ + 0.02 M NaClO_4 at pH 5.

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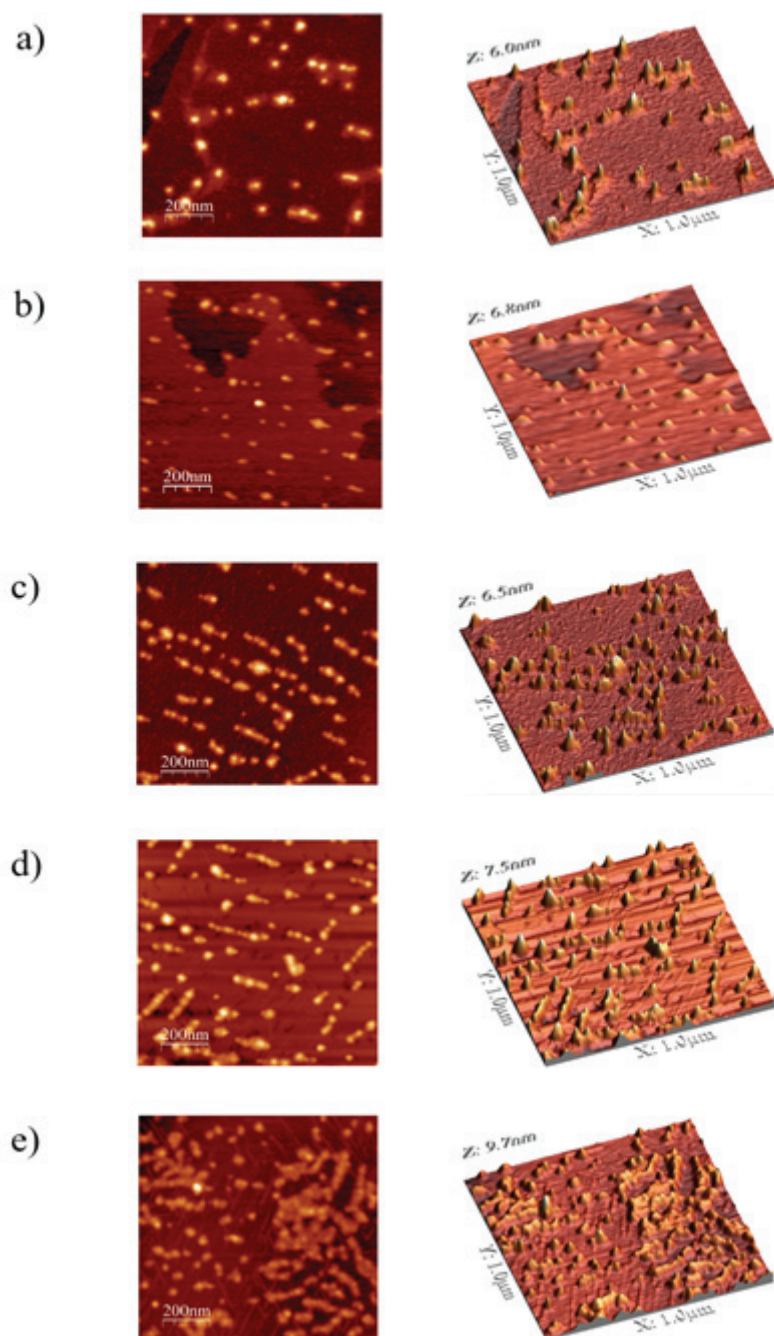


Fig. S-2. AFM images of copper cluster's sizes obtained at: a) -0.075 , b) -0.100 , c) -0.125 , d) -0.150 and f) -0.175 V applied potentials from a plating bath containing 0.01 M $\text{Cu}(\text{ClO}_4)_2$ + 0.02 M NaClO_4 at pH 5.

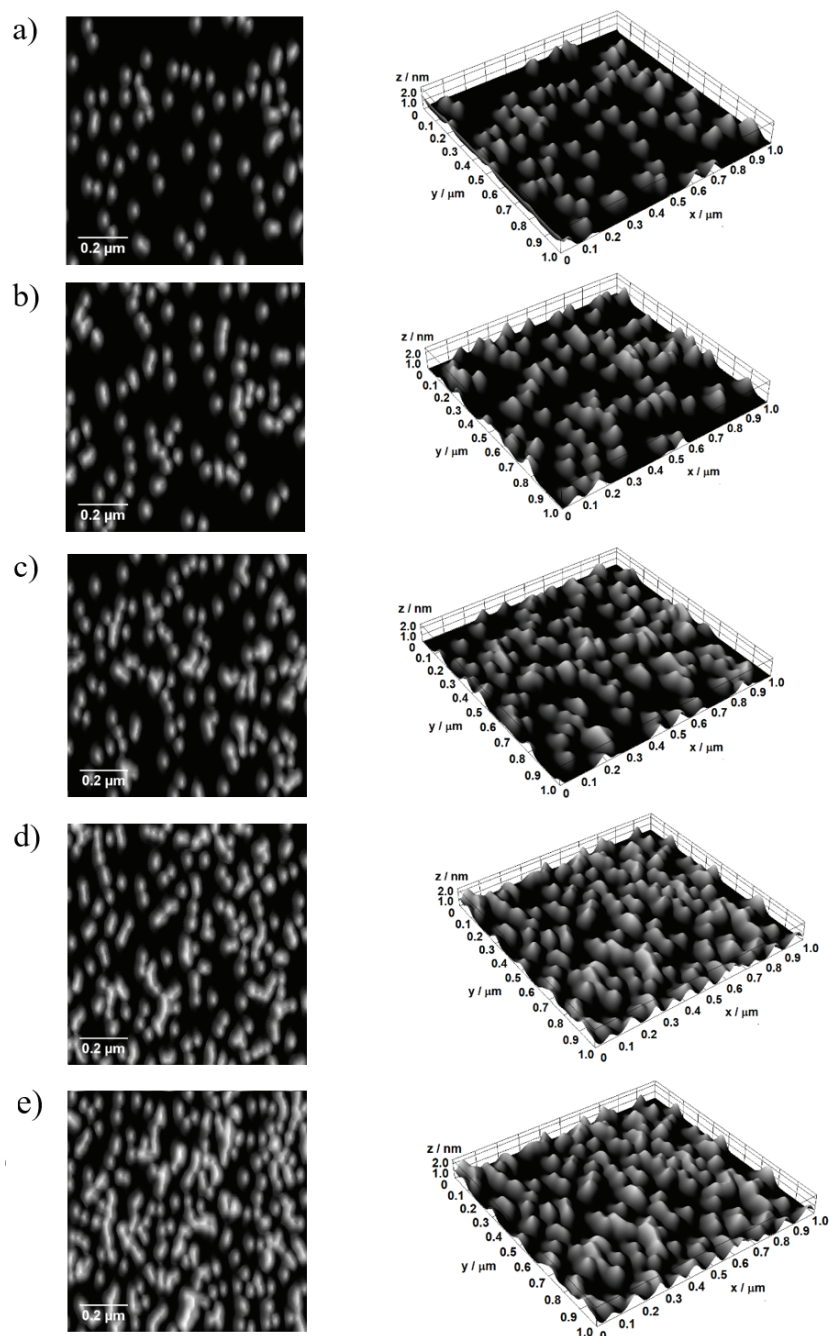


Fig. S-3. Simulation of the distribution of the copper cluster nuclei per μm^2 , according to Eq. (3) at the potential values of a) -0.100, b) -0.125, c) -0.150, d) -0.175 and e) -0.200 V, considering a random distribution of the nuclei on the HOPG surface.